

Appl. No. 09/992,387  
Amdt. dated Feb.1, 2006  
Reply to Office action of Nov. 3, 2005

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-24. (canceled)

25. (previously presented) A device comprising:

an integrated circuit chip having a plurality of contact pads;  
a single-layered insulating film having a top surface and a bottom surface;  
an electrically conductive pattern formed of a conductive film disposed on the top surface of the insulating film;  
vias extending through the interposer filled with conductive material, contacting the conductive pattern, and forming exit ports on the bottom surface;  
the bottom surface immediately adjacent the exit ports free of a conductive pattern and contact pad; and  
thermo-compressed electrical coupling members disposed between the contact pads and conductive lines, connecting the chip to the interposer.

26. (previously presented) The device of claim 25, further comprising solder balls attached to the exit ports.

27. (previously presented) The device of claim 25, further comprising encapsulating material encapsulating the integrated circuit chip.

28. (previously presented) A substrate for connecting an integrated circuit chip having a plurality of contact pads, comprising:

a single-layered insulating interposer film having a top surface and a bottom surface;  
an electrically conductive pattern formed of a conductive film disposed on the top surface of the insulating interposer film;  
vias extending through the interposer, filled with conductive material, contacting the conductive pattern, and forming exit ports on the bottom surface; and

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the bottom surface immediately adjacent the exit ports free of a conductive pattern and contact pad.

29. (previously presented) The substrate in claim 28, further comprising solder balls attached to the exit ports.
30. (previously presented) The substrate in claim 28, in which the conductive pattern includes attachment sites corresponding to contact pads on the integrated circuit chip.
31. (previously presented) A device comprising a substrate in claim 28, and an integrated chip attached to the substrate.
- 32-37. (canceled)